LMH1981,LMH1982

Application Note 1893 Demonstrating SMPTE-Compliant SDI Output Jitter

Using the LMH1982 and Virtex-5 GTP Transmitter



Literature Number: SNLA110

Demonstrating SMPTE-Compliant SDI Output Jitter Using the LMH1982 and Virtex-5 GTP Transmitter

Introduction

As 3-Gbps serial digital interface (SDI) gains adoption in professional and broadcast video equipment to enable fastframe 1080p HD video over a single link, the need for flexible and high-performance video clock generation becomes critical to reliably transmit and receive triple-rate (3G/HD/SD) SDI video. This is especially true for multi-channel video equipment using SDI serializers and deserializers based on the serial transceivers in high-end FPGAs, such as Xilinx's Virtex-5 LXT. Because FPGA-based serializers virtually transfer any jitter on its reference clock input to its serial data output, they require very low-jitter reference clocks to meet the SMPTE-specified SDI output jitter requirements.

This application note demonstrates SMPTE-compliant SDI output jitter with a Virtex-5 reference design using low-jitter reference clocks from National Semiconductor's LMH1982 video clock generator. The reference design included a SD/ HD video pattern generator and a multi-rate SDI serializer using the Virtex-5 RocketIO GTP transceiver. The demo was implemented on Xilinx's ML571 Virtex-5 Serial Digital Video (SDV) Demo Board. National's LMH1982SQEEVAL Evalua-

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tion Board, which includes the LMH1981 sync separator and LMH1982, was used to generate an external genlock clock for the demo. To interface this external clock to the ML571 board, a CTCMSMA Plug-in Clock Module with SMA connectors (from Cook Technologies) was also required.

Demo Overview

Figure 1 shows a block diagram of the entire demo setup with the test and measurement equipment. A Tektronix TG700 test signal generator was used to generate an analog reference input signal, such as SD composite black-burst or HD tri-level sync. This was fed to the LMH1981, which extracted the sync signals required by the LMH1982. A host PC with the LMH1982 Evaluation Software (GUI) was used to program the genlock configuration and reference clock rate according to the selected reference input and SDI output format. After the SDI output was frequency-locked to the reference input, the SDI output jitter was measured on a Tektronix WFM7100 set for both "Timing Jitter" and "Alignment Jitter" high pass filters (HPF).

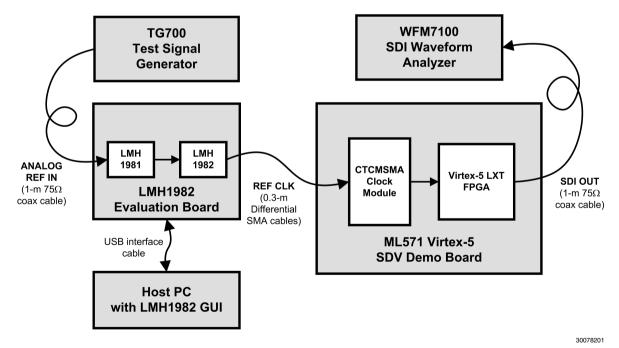


FIGURE 1. Overview of Demo Setup

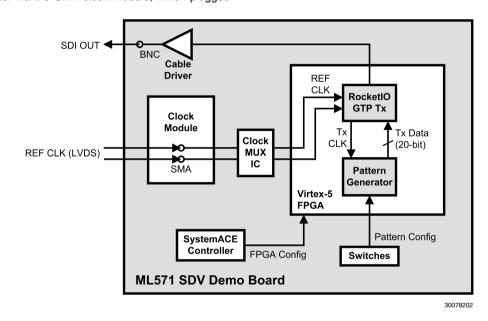
FPGA Reference Design

In the multi-rate SDI transmitter reference design, a reference clock is required for clocking the GTP transmitter (Tx) to generate and transmit a color bars or SDI checkfield test pattern signal. Two different clock rates, 148.5 MHz and 148.5/1.001 MHz, are used to support the various SDI output formats supported by this demo. The 148.5 MHz clock rate is needed to transmit HD-SDI at 1.485 Gbps and also SD-SDI. The SD-SDI transmitter uses 11x over-sampling (11 x 270 Mbps) to realize an effective bit rate of 2.97 Gbps, which also corresponds to the clock rate x 20. The 148.5/1.001 MHz clock rate is needed to transmit HD-SDI at 1.485/1.001 Gbps, where the 1.001 factor denotes rate compatibility with the NTSC system. The LMH1982 provided the external reference clock to the GTP transmitter via the SMA clock module, which plugged

into the ML571 board. *Figure 2* shows a simplified block diagram of the reference design and reference clock routing implemented on the ML571.

The reference design was loaded to the FPGA via the SystemACE controller included on the ML571. Once loaded, the FPGA demo was controlled using on-board switches to select the output SDI standard, bit rate, video format, and video pattern. The reference input format and clock rate were selected and programmed to the LMH1982 according to the SDI output format evaluated.

For more complete descriptions of the multi-rate SDI transmitter reference design example used in this demo, please consult Xilinx's XAPP514 SDI reference design manual or contact their Application Support.





HD-SDI Output Jitter Hypothesis

Based on the inference of reference clock jitter on the transmitter's output performance, it is possible estimate the HD-SDI output alignment jitter from the typical clock jitter specs of the LMH1982. The "Alignment Jitter" spec defined by SMPTE standards for HD-SDI output signals specifies high-frequency spectral components above 100 kHz. The LMH1982 datasheet specifies clock jitter components above 10 kHz using the time interval error (TIE) method. The LMH1982's typical clock output jitter is 45 ps p-p for the 148.5 MHz clock and 60 ps p-p for the 148.5/1.001 MHz clock.

Therefore, it would be a reasonable hypothesis to expect HD-SDI output alignment jitter as low as 0.07 UI, or 45 ps p-p, for formats based on the 148.5 MHz clock and as low as 0.09 UI, or 60 ps p-p, for formats based on the 148.5/1.001 MHz clock.

NOTES ON CLOCK JITTER

• The LMH1982 jitter specs quoted earlier assume that the external 27 MHz VCXO clock jitter is ≤20 ps p-p and the SD clock output is disabled.

 Refer to Appendix A. Loop Response Design for information regarding loop response design requirements to meet the SDI output "Timing Jitter" spec, which defines low-frequency spectral components above 10 Hz.

SDI Jitter Measurement Results

Using ordinary ML571 and LMH1982 boards, the output jitter was measured for the two major SD-SDI formats and two popular 1080i HD-SDI formats. 3G-SDI was not evaluated in this demonstration because the SDI reference design and the WFM7100 did not support 3G formats. See *Appendix B. SDI Eye & Jitter Plots* for screen captures of the SDI output eye and jitter plots from the WFM7100.

Table 1 shows a summary of the measured SDI output jitter as well as the SMPTE jitter specs, and the corresponding reference clock and reference input conditions. In every case, the measured jitter was less than half of the spec limit for both standards. HD-SDI jitter performance was evaluated using both SD and HD reference inputs; however, the eye/jitter plots were only captured for the HD reference inputs.

TABLE 1. Summary of SDI Jitter Measurements

	SD-SDI		HD-SDI		HD-SDI	
SDI Output	270 Mbps		1.485/1.001 Gbps		1.485 Gbps	
	525i 59.94	625i 50	1080i 59.94		1080i 50	
Output Format / Pattern	RP 178 ¹	RP 178 ¹	75% Color Bars		75% Color Bars	
SDI Eye & Jitter Plot	Figure 4	Figure 5	n/a ²	Figure 6	n/a ²	Figure 7
Timing Jitter Data (p-p)	0.06 UI	0.07 UI	0.13 UI	0.13 UI	0.12 UI	0.13 UI
Alignment Jitter Data (p-p)	0.06 UI	0.06 UI	0.09 UI	0.09 UI	0.07 UI	0.07 UI
			(61 ps)	(61 ps)	(47 ps)	(47 ps)
SDI Standard	SMPTE 259M-2006 < 0.2 UI < 0.2 UI 148.5 MHz 45 ps ³		SMPTE 292M-1998			
Timing Jitter Spec (p-p)			< 1.0 UI			
Alignment Jitter Spec (p-p)			< 0.2 UI			
Reference Clock			148.5/1.001 MHz		148.5 MHz	
Datasheet Typ. Clock Jitter (p-p)			60 ps ³		45 ps ³	
Reference Input Format	NTSC	PAL	NTSC	1080i 59.94	PAL	1080i 50

¹ Refers to the "SDI Checkfield" test pattern specified in SMPTE RP 178-1996. 75% Color Bars was not a selectable SD test pattern option.

² HD-SDI eye/jitter plots were not captured for the SD reference input conditions.

³ ICP2 and ICP3 register settings (register 14h) were both programmed to a value of 2 to reduce the charge pump current of PLL 2 and PLL 3, respectively, and thus lower their respective loop bandwidths. This effectively reduced the high-frequency jitter on the 148.5 MHz and 148.5/1.001 MHz clocks to improve HD-SDI output jitter in the alignment jitter frequency band.

Conclusions

These results demonstrate SMPTE-compliant jitter performance for SD-SDI and HD-SDI using the Virtex-5 RocketIO GTP transmitter with the LMH1981 and LMH1982 genlock clocking solution. There appears to be negligible jitter contribution from the GTP transmitter since there is only small difference between HD-SDI alignment jitter (converted to ps p-p) and the typical reference clock jitter spec. For example, the HD-SDI alignment jitter for 1080i 50 is 0.07 UI p-p, or 47 ps, and the typical LMH1982 clock jitter for 148.5 MHz is 45 ps, which gives an estimated jitter contribution of +2 ps from the GTP transmitter. Therefore, the HD-SDI output alignment jitter data corroborates the earlier stated hypothesis. Moreover, a reasonable approximation can now be made for 3G-SDI output jitter based on the measured HD-SDI jitter results. Two of the 3G-SDI formats, 1080p 59.94 and 1080p 50, operate at exactly twice the bit rate of the two HD-SDI formats measured. Using the same LMH1982 clocks and a similar GTP transmitter reference design with a 1080p pattern generator, the 3G-SDI output jitter could be extrapolated by doubling the measured HD-SDI jitter for both bit rates.

Table 2 shows the 3G-SDI jitter approximated from the HD-SDI jitter measurements. Additionally, the 3G-SDI output alignment jitter could have been estimated directly from the LMH1982's clock jitter specs, as previously shown in *HD-SDI Output Jitter Hypothesis*.

TABLE 2. 3G-SDI Jitter Estimates

SDI Output	HD-SDI	HD-SDI	3G-SDI	3G-SDI	
SDI Output	1.485/1.001 Gbps	1.485 Gbps	2.97/1.001 Gbps	2.97 Gbps	
Output Format	1080i 59.94	1080i 50	1080p 59.94	1080p 50	
Timing Jitter (p-p)	0.13 UI	0.13 UI	0.26 UI	0.26 UI	
Timing Sitter (p-p)	(measured)	(measured)	(estimate)	(estimate)	
Alignment Jitter (p-p)	0.09 UI	0.07 UI	0.18 UI	0.14 UI	
	(measured)	(measured)	(estimate)	(estimate)	
SDI Standard	SMPTE 292M-1998		SMPTE 424M-2006		
Timing Jitter Spec (p-p)	< 1.0 UI		< 2.0 UI		
	< 0.2 UI		< 0.3 UI		
Alignment Jitter Spec (p-p)			(< 0.2 UI recommended)		
Reference Clock	148.5/1.001 MHz	148.5 MHz	148.5/1.001 MHz	148.5 MHz	
Reference Input Format	1080i 59.94	1080i 50	1080i 59.94	1080i 50	

Summary

This application note demonstrated the capability of the LMH1981 and LMH1982 to implement low-jitter genlock reference clocks for the Virtex-5 GTP transmitter in a multi-rate video pattern generator demo on the ML571 platform. The

HD-SDI output alignment jitter was estimated from the LMH1982's clock jitter specs and ultimately verified from the HD-SDI jitter measurement results. Lastly, the HD-SDI jitter measurements were used to approximate 3G-SDI output jitter performance.

Appendix A. Loop Response Design

The LMH1982 relies on its VCXO PLL (PLL 1) to phase-lock the external 27 MHz VCXO clock to the analog reference input in genlock mode. The VCXO clock also provides a stable 27 MHz source for its internal VCO PLLs to generate the 148.5 and 148.5/M MHz output clock rates. Jitter on the VCXO clock could easily transfer to the output clock with little or no attenuation. Therefore, proper design of PLL 1's loop response is necessary to minimize VCXO clock and output clock jitter. The loop response, characterized by the nominal –3 dB loop bandwidth (BW) and damping factor (DF), was designed using the external loop filter and other PLL parameters programmed with the LMH1982 GUI.

Figure 3 shows a simplified block diagram of the LMH1982 board with the LMH1981, external VCXO, and loop filter. The loop filter component values were derived using the loop response analysis described below.

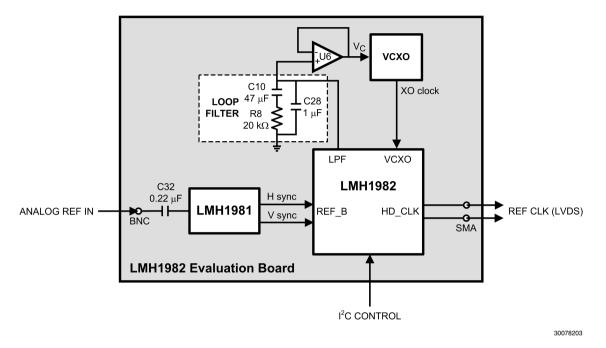


FIGURE 3. LMH1982 Evaluation Board with Loop Filter Implementation

To design the loop response, it was critical to initially identify and analyze the fundamental jitter characteristics related to PLL 1: 1) VCXO clock jitter requirement, 2) input H sync jitter amplitude and frequencies, and 3) jitter transfer function characteristics.

- The VCXO clock jitter was targeted for no greater than 20 ps p-p to minimize jitter degradation on the output clock. This was denoted in the clock jitter spec test conditions in the LMH1982 datasheet.
- The input H sync jitter was expected to occur predominantly at the reference input line and frame rates, and have jitter amplitude no greater than 2 ns p-p. To realize this level of input jitter, the LMH1981's input coupling capacitor (C32) value was modified to 0.22 uF, as indicated in the LMH1981 datasheet.
- The jitter transfer function for PLL 1 exhibits a roll-off rate of -40 dB/decade at frequencies much higher than the -3 dB BW (e.g. above 1 decade). At frequencies near the BW, peaking in the transfer function can be minimized by maintaining a DF value between 0.707 and 1.0.

Based on the above analysis, it was determined to set the BW to 3 Hz to provide at least 40 dB of jitter attenuation at frequencies at 25-30 Hz (reference input frame rate) and above.

The DF was set to at least 0.80 to ensure good loop stability and minimal jitter peaking. Using the LMH1982 datasheet's loop response design methodology and design equations (below), the loop filter component values were derived (see R8, C10, and C28 in *Figure 3*).

$$BW = I_{CP1} * R_{S} * K_{VCO} / FB_DIV$$
$$DF = R_{S} / 2 * sqrt (I_{CP1} * C_{S} * K_{VCO} / FB_DIV)$$

where:

- I_{CP1} Nominal PLL 1 charge pump current (programmable)
- **R**_S Nominal resistor value of R8
- $\mathbf{K_{VCO}}$ 1000 Hz/V VCXO gain for CTS VCXO p/n 357L-BC27M0000
- FB_DIV Feedback divider value
- C_s Nominal capacitor value of C10

The estimated loop response characteristics for PLL 1 are shown in *Table 3*. In order to maintain consistent BW and DF values across all reference input formats, the charge pump current for PLL 1 needed to be programmed accordingly for each format using the LMH1982 GUI.

TABLE 3. Estimated PLL 1 Loop Response Characteristics

Reference Input Format	NTSC	PAL	1080i 59.94	1080i 50
Reference Divider	1	1	5	1
Feedback Divider	1716	1728	4004	800
ICP1 Control Register Setting (decimal)	8	8	19	4
ICP1 Current	250 µA	250 µA	594 µA	125 µA
Est. Loop Bandwidth	3 Hz	3 Hz	3 Hz	3 Hz
Est. Damping Factor	0.83	0.82	0.83	0.86

LOOP FILTER CAPACITORS

It is suggested to use tantalum capacitors for C10 and C28 instead of ceramic capacitors in the PLL loop filter, which is a sensitive analog circuit. Ferroelectric ceramics, such as X7R, X5R, Y5V, Y5U, etc., exhibit piezoelectric effects that generate electrical noise in response to mechanical vibration and

shock. This electrical noise can modulate the VCXO control voltage and consequently induce clock jitter at high amplitudes when the board and ceramic components are subjected to vibration or shock. Tantalum capacitors can be used to mitigate this effect.

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Appendix B. SDI Eye & Jitter Plots

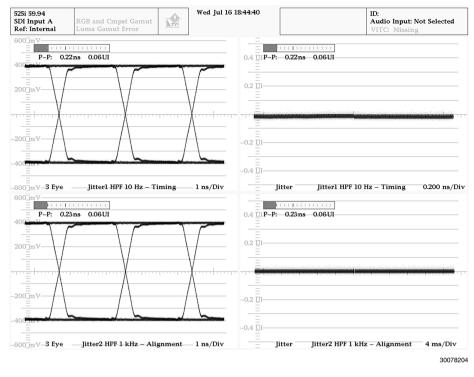
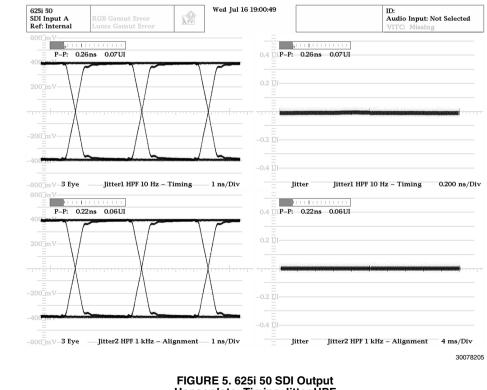
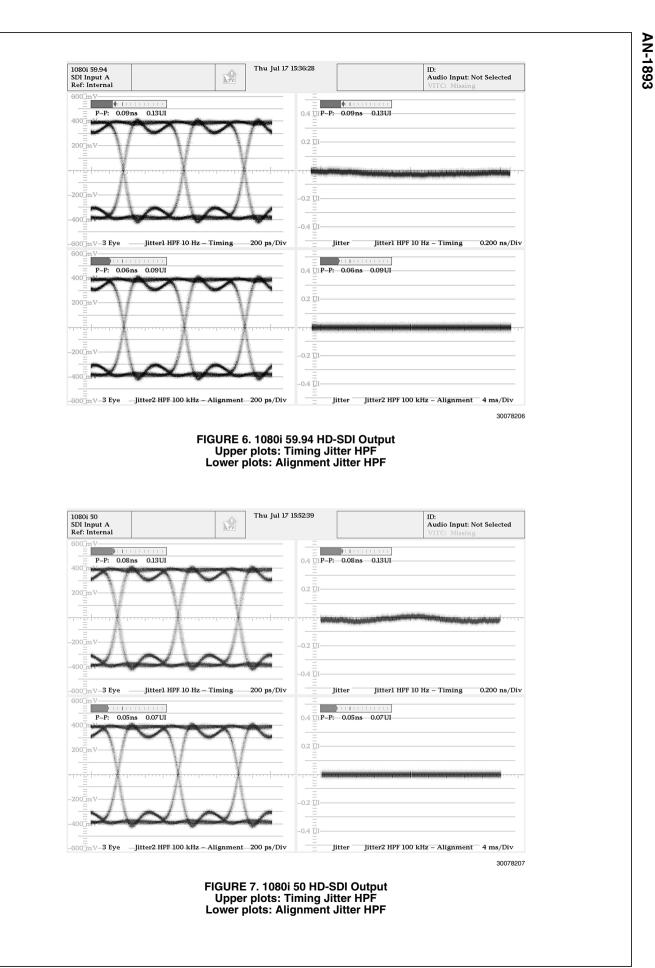


FIGURE 4. 525i 59.94 SDI Output Upper plots: Timing Jitter HPF Lower plots: Alignment Jitter HPF



Upper plots: Timing Jitter HPF Lower plots: Alignment Jitter HPF



Resources

- AN-1841 LMH1982 Evaluation Board User Guide, http:// www.national.com/an/AN/AN-1841.pdf
- LMH1982 Product Page, http://www.national.com/pf/LM/ LMH1982.html
- LMH1981 Product Page, http://www.national.com/pf/LM/ LMH1981.html
- ML571-1982CLK Video Clock Module Product Page, http://www.national.com/analog/interface/sdi_timing
- Xilinx ML571 SDV Demo Board Page, http://www.cooktech.com/ctxil406.html

- Improving Video Clock Generation in Modern Broadcast Video Systems, http://www.national.com/nationaledge/ jul06/AnalogEdge4_7.pdf
- XAPP514 v4.0 Xilinx Virtex A/V Connectivity Solutions App Note, http://www.xilinx.com/support/documentation/ application_notes/xapp514.pdf
- SMPTE 259M-2006 SD-SDI Standard
- SMPTE 292M-1998 HD-SDI Standard
- SMPTE 424M-2006 3G-SDI Standard

Notes

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Notes

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